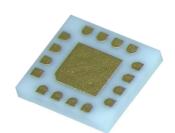
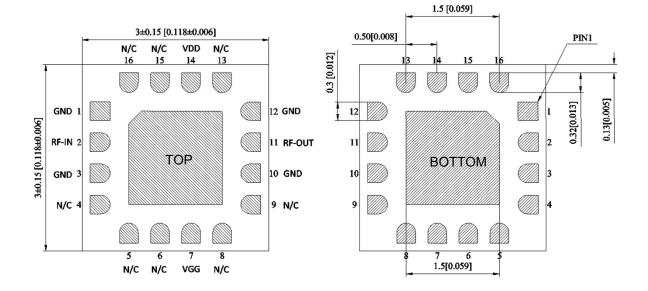


Ceramic QFN 3x3mm Package



Dimensions and pin description:





Notes:

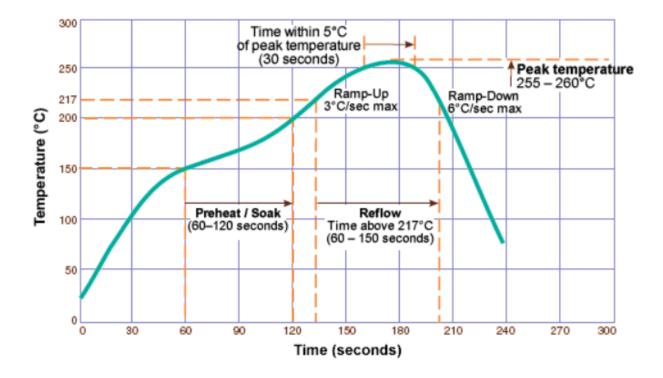
- 1. Pad plating Ni: 1.27-8.89um Au: 0.3um min
- 2. Dimension shown in mm [inch] Tolerances $\pm 0.05 \text{mm}$ [$\pm 0.002 \text{inch}$]

Pin Descriptions		
Pin Number	Function	Description
2	RF-IN	This pad is DC coupled and matched to 50 Ohms
11	RF-OUT	RF output for amplifier
14	VDD	Connect DC bias (Vdd) network toprovide drain current (ldd)
7	VGG	Gate control for amplifier
1,3,10,12,	GND	These pins & exposed ground paddle must be connected to RF/DC ground
Die Bottom	GND	Die bottom must be connected to RF/DC ground



Ceramic QFN 3x3mm Package

Recommended lead-free reflow temperature curve:



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